



Flexible Electronic Materials and Devices: Preparation and Application

Guest Editor:

Dr. Shu-Jen Wang

Department of Physics, Hong
Kong Baptist University, Kowloon
Tong, Hong Kong, China

Deadline for manuscript
submissions:

20 October 2024

Message from the Guest Editor

Dear Colleagues,

Flexible electronics have advanced significantly in the past decade, enabling their application in numerous domains where conventional rigid electronics cannot be applied, such as bioelectronics and electronic sensors, etc. Two main strategies have been proposed to introduce flexibility in electronic materials: reducing the thickness of commercially available inorganic semiconductor materials and designing novel semiconductor materials with intrinsic mechanical flexibility. Further advances in flexible electronic devices would require the matrimony of material synthesis, device physics and engineering, and advanced characterization expertise to enable the development of high-performance devices with decent reliability for practical real-world applications.

This Special Issue aims to compile research papers, short communications, and review articles focused on the synthesis of novel materials, device design, fabrication, and the advanced characterization of various flexible electronic devices for the identification of the main milestones in the roadmap of future flexible electronics research.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

Journal Rank: JCR - Q1 (Metallurgy and Metallurgical Engineering) / CiteScore - Q2 (*Condensed Matter Physics*)

Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
[X@Materials_Mdpi](https://twitter.com/Materials_Mdpi)